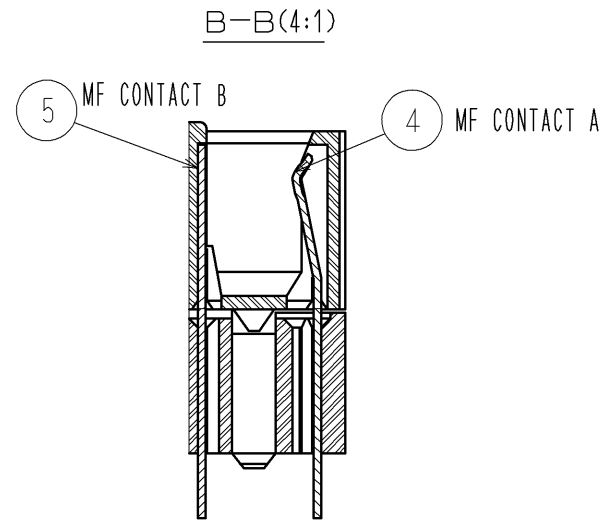
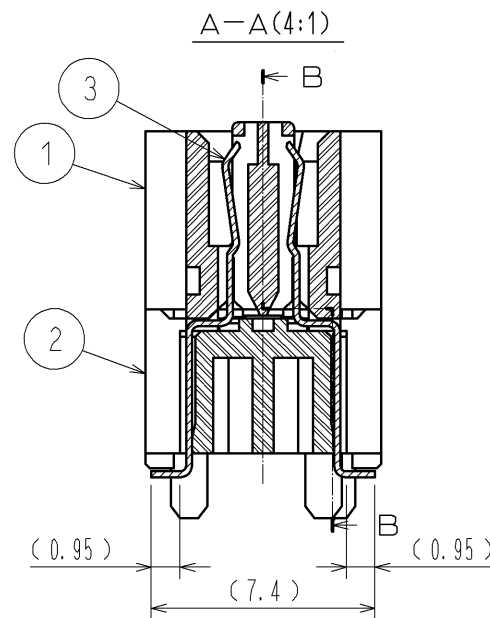
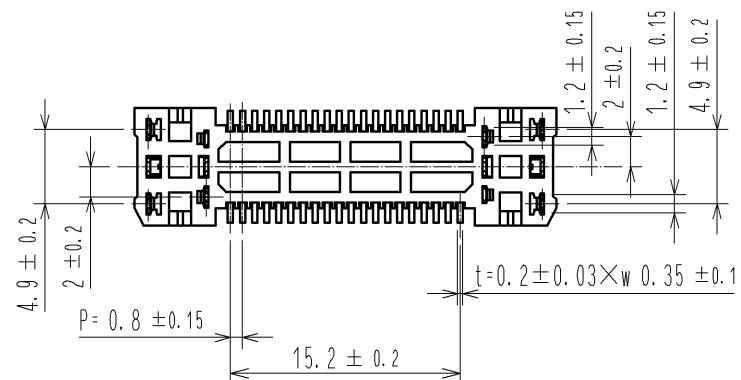
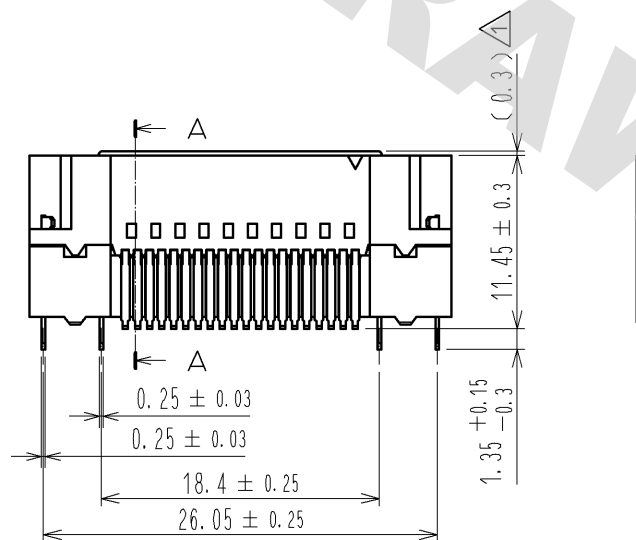
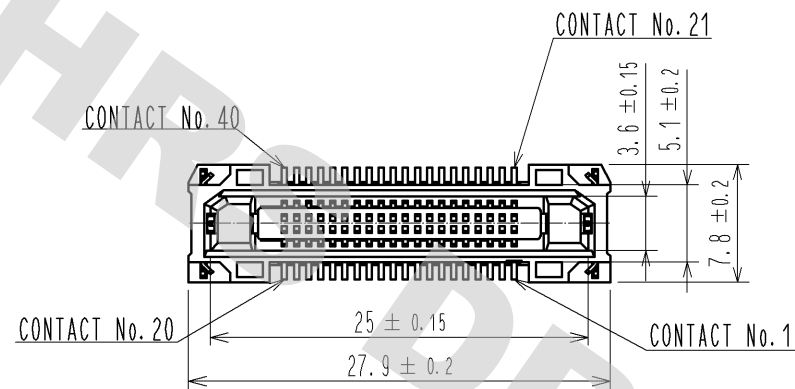
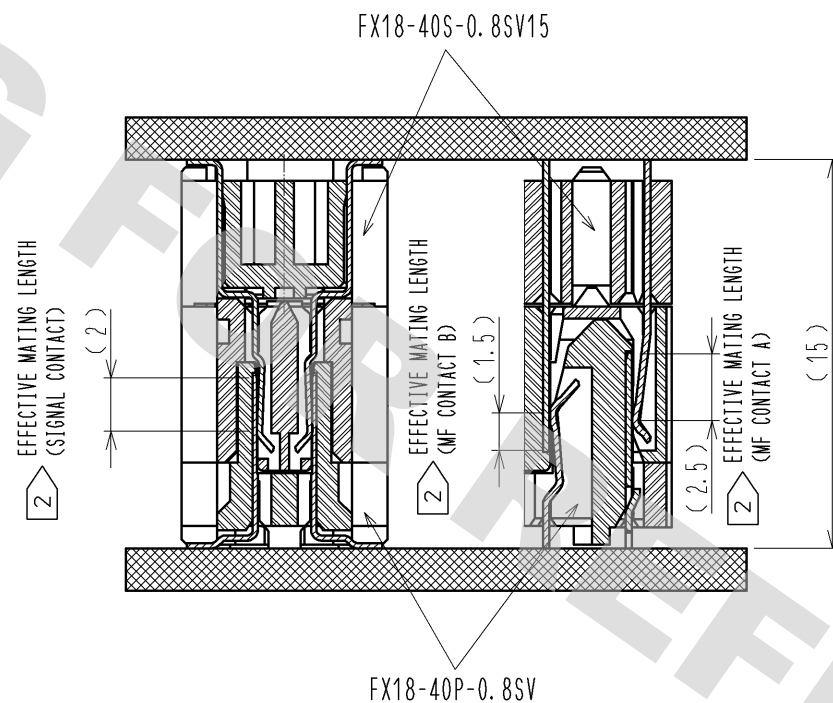


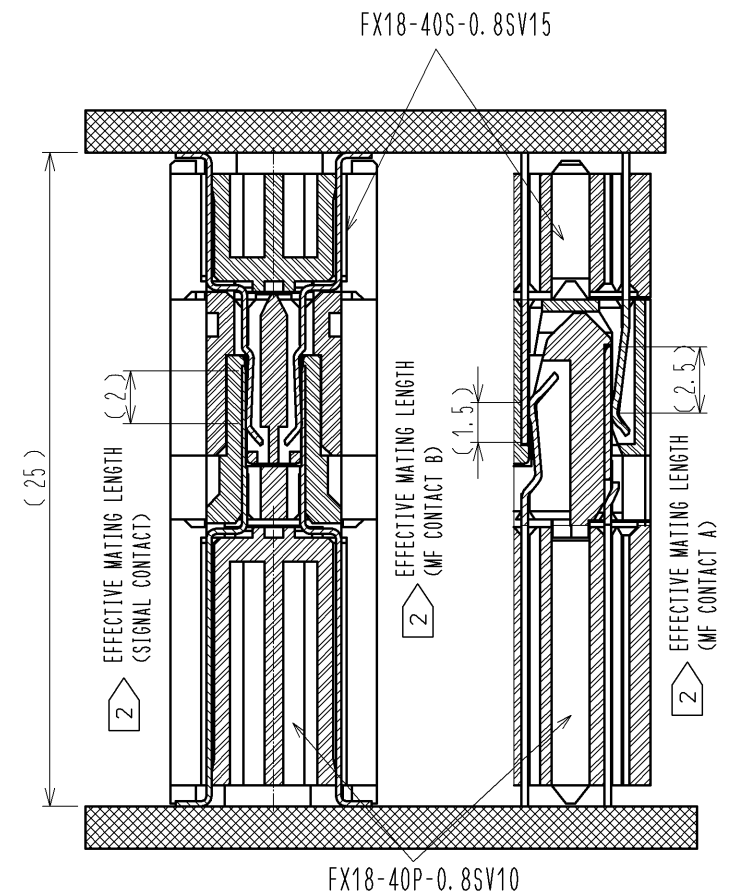
DRAWING FOR REFERENCE: This is subject to change without notice
08/11/2012



CROSS SECTION OF MATING(FREE)
STACKING HEIGHT=15mm



CROSS SECTION OF MATING(FREE)
STACKING HEIGHT=25mm



NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.

2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B)
WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.

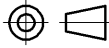
3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)

4 IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)
REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.

5 THIS IS PACKAGED IN TRAY. (60pcs/TRAY)

6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.

7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm		5	COPPER ALLOY	LEAD AREA:TIN-PLATING 1 μm							
		LEAD AREA:GOLD 0.03 μm				UNDER PLATING:NICKEL 1.3 μm							
		UNDER PLATING:NICKEL 1.3 μm											
2	POLYAMIDE	BLACK UL94V-0		4	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm							
1	POLYAMIDE	BLACK UL94V-0				LEAD AREA:TIN-PLATING 1 μm							
						UNDER PLATING:NICKEL 1.3 μm							
NO.	MATERIAL		FINISH , REMARKS		NO.	MATERIAL		FINISH , REMARKS					
UNITS mm				SCALE 2 : 1		COUNT 4	DESCRIPTION OF REVISIONS DIS-F-005578		DESIGNED TH. SANO	CHECKED KI. HIROKAWA	DATE 11.07.21		
 HIROSE ELECTRIC CO., LTD.		APPROVED : HS. OKAWA		11.03.18		DRAWING NO. EDC3-334386-00							
		CHECKED : KI. HIROKAWA		11.03.18		PART NO. FX18-40S-0.8SV15							
		DESIGNED : TH. SANO		11.03.18		CODE NO. CL579-0026-3-00							
		DRAWN : TH. SANO		11.03.18									
													

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08/11/2012

